



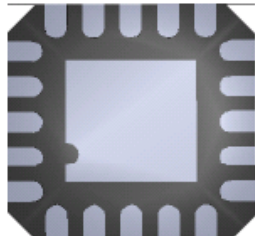
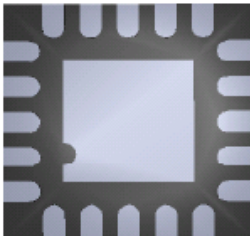
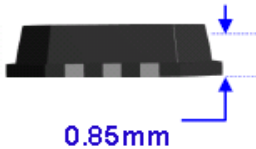
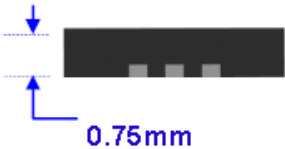
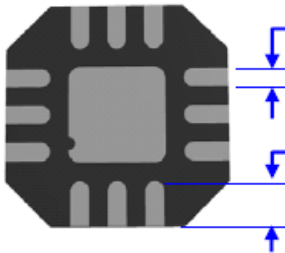
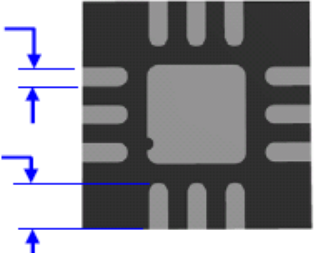


Bill of Materials and Package Configuration

Material	FROM	TO	Remarks
	Amkor - Korea	Amkor - Philippines	
Die Attach	Ablestik 8290	Ablestik 8290	Same
Wire	Au	Au	Same
Mold Compound	Sumitomo G700	Sumitomo G700	Same
Leadframe	C194	C194	Same
Package: Side			Punch: Flange Sawn: Square
Top			Sawn: • Pin 1 is Laser Marked • Square Edge
Bottom			Same Foot Print

Package Dimensions

PUNCH	SAWN	
		Package Thickness Difference
		Exposed Pad, Lead Length and Lead Width dimensions remains within tolerance.

Body Size (mm)	Lead Count	Lead Pitch (mm)	Punch LFCSP POD	Sawn LFCSP POD	Exposed Pad Size (mm)
3 x 3	8	0.5	CP 8-2	CP 8-13	1.74 x 1.45
			CP 8-9	CP 8-20	2.13 x 1.5
	12	0.5	CP 12-1	CP 12-4	1.3 x 1.3
			CP 12-3	CP 12-5	1.5 x 1.5
	16	0.5	CP 16-2	CP 16-21	1.3 x 1.3
			CP 16-3	CP 16-27	1.5 x 1.5

Reliability Qualification Results of 3x3 sawn LFCSP package at ATP

QUALIFICATION RESULTS			
TEST	CONDITIONS	SAMPLE SIZE	RESULTS
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 77	Pass
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	Pass
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 77	Pass
Solder Heat Resistance (SHR)*	<i>JEDEC/IPC J-STD-020</i>	3 x 11	Pass

*These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 1 preconditioning consists of the following: Bake: 24 hrs @ 125°C, Soak: Unbiased Soak: 192 hrs @ 30°C, 60%RH, Reflow: 3 passes through an oven with a peak temperature of 260°C.